

## Photo DMOS-FET Relay

### Description

The **LT745** is a 2-Form A solid state relay in a 8 pin SMD package that employs optically coupled MOSFET technology to provide 3750V/5000V of input to output isolation. The optically coupled input is controlled by a highly efficient GaAlAs infrared LED and MOS FETs on the output side.

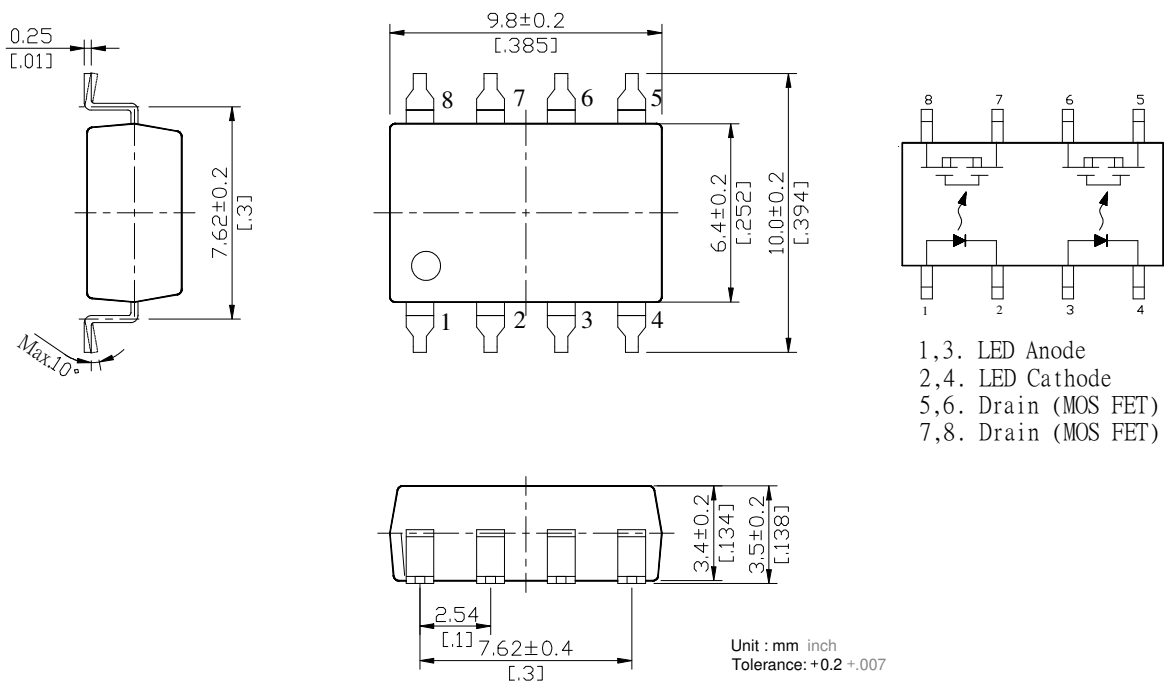
### Features

- Low driver power requirements (TTL/CMOS Compatible)
- High reliability
- Arc-Free with no snubbing circuits
- 3750/5000Vrms Input/Output isolation
- Tape & Reel version available

### Applications

- Telecommunications (PC, Electronic notepad)
- Measuring and Testing equipment
- Industrial control
- Security equipments
- High speed inspection machine

### Outline Dimensions



## Photo DMOS-FET Relay Specifications

### Part Name: LT745

(Load voltage: 400V / Load current: 130mA)

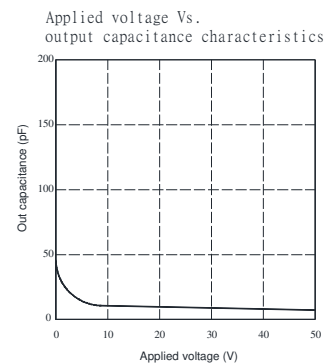
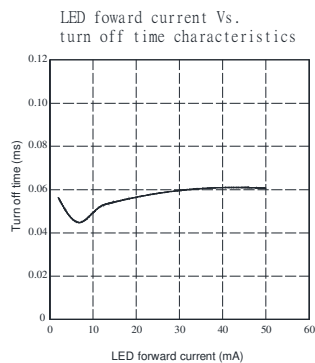
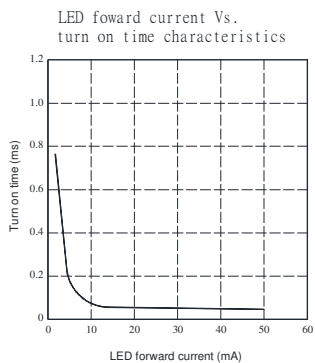
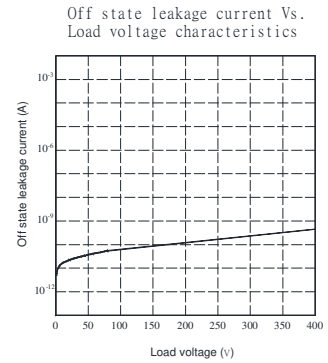
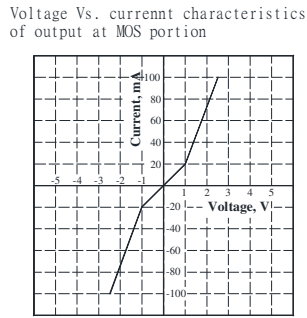
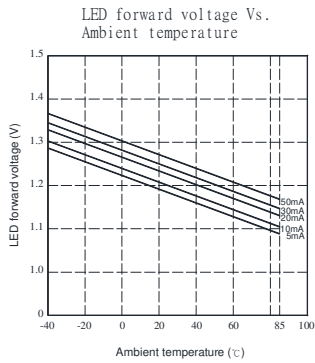
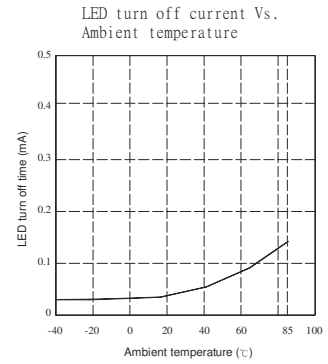
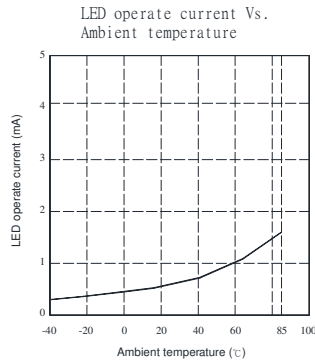
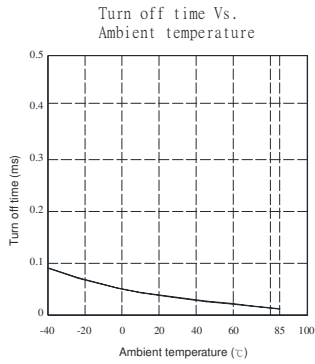
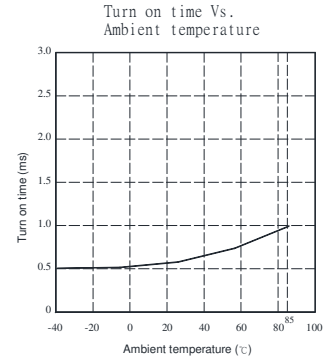
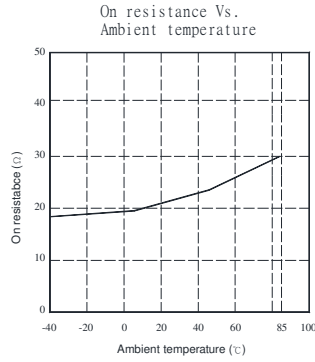
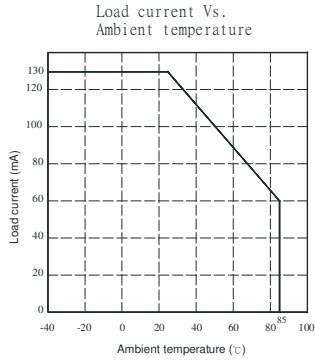
#### Absolute Maximum Ratings (Ambient Temperature: 25°C)

| Item                            | Symbol                   | Value             | Units            | Note                      |
|---------------------------------|--------------------------|-------------------|------------------|---------------------------|
| Input                           | Continuous LED Current   | I <sub>F</sub>    | 50               | mA                        |
|                                 | Peak LED Current         | I <sub>FP</sub>   | 1000             | mA<br>f=100Hz,<br>duty=1% |
|                                 | LED Reverse Voltage      | V <sub>R</sub>    | 5                | V                         |
|                                 | Input Power Dissipation  | P <sub>In</sub>   | 75               | mW                        |
| Output                          | Load Voltage             | V <sub>L</sub>    | 400              | V(AC peak or DC)          |
|                                 | Load Current             | I <sub>L</sub>    | 130              | mA                        |
|                                 | Peak Load Current        | I <sub>Peak</sub> | 0.6              | A<br>100ms(1 pulse)       |
|                                 | Output Power Dissipation | P <sub>out</sub>  | 300              | mW                        |
| Total Power Dissipation         | P <sub>T</sub>           | 350               | mW               |                           |
| I/O Breakdown Voltage           | V <sub>I/O</sub>         | 3750              | V <sub>rms</sub> | RH=60%, 1min              |
| I/O Breakdown Voltage(Suffix-V) | V <sub>I/O</sub>         | 5000              | V <sub>rm</sub>  | RH=60%, 1min              |
| Operating Temperature           | T <sub>Opr</sub>         | -40 to +85        | °C               |                           |
| Storage Temperature             | T <sub>Stg</sub>         | -40 to +100       | °C               |                           |
| Pin Soldering Temperature       | T <sub>Sol</sub>         | 260               | °C               | 10 sec max.               |

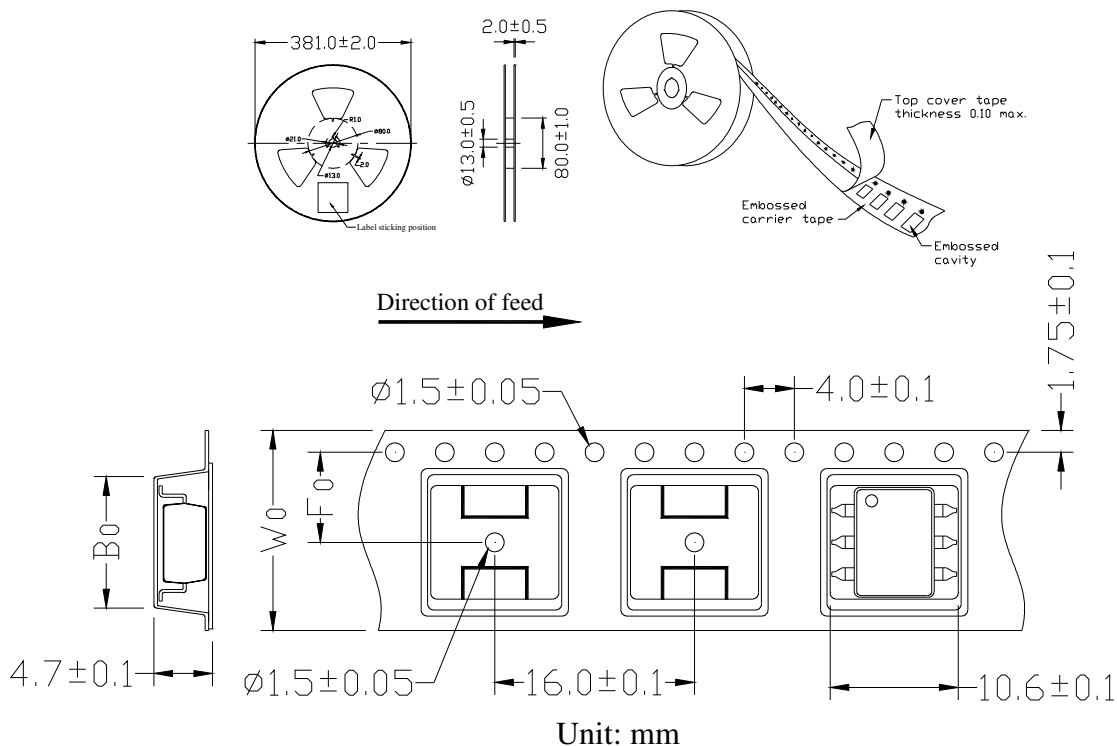
#### Electrical Specifications (Ambient Temperature: 25°C)

| Item             | Symbol                    | MIN.               | TYP.             | MAX. | Units | Conditions  |
|------------------|---------------------------|--------------------|------------------|------|-------|---|
| Input            | LED Forward Voltage       | V <sub>F</sub>     | 1.2              | 1.5  | V     | I <sub>F</sub> =10mA  |
|                  | Operation LED Current     | I <sub>F On</sub>  | 0.5              | 5.0  | mA    |   |
|                  | Recovery LED Current      | I <sub>F Off</sub> | 0.35             | 0.5  | mA    |   |
|                  | Recovery LED Voltage      | V <sub>F Off</sub> | 0.7              |      | V     |   |
| Output           | On-Resistance             | R <sub>On</sub>    | 20               | 30   | Ω     | I <sub>F</sub> =10mA, I <sub>L</sub> = Rating,<br>Time to flow is within 1 sec. |
|                  | Off-State Leakage Current | I <sub>Leak</sub>  |                  | 1    | uA    | V <sub>L</sub> =Rating  |
|                  | Output Capacitance        | C <sub>Out</sub>   |                  | 45   | pF    | V <sub>L</sub> =0, f=1MHz   |
| Transmis<br>sion | Turn-On Time              | T <sub>On</sub>    | 0.5              | 1.0  | ms    | I <sub>F</sub> =10mA, I <sub>L</sub> =Rating                                    |
|                  | Turn-Off Time             | T <sub>Off</sub>   | 0.03             | 0.5  | ms    |   |
| Coupled          | I/O Isolation Resistance  | R <sub>I/O</sub>   | 10 <sup>10</sup> |      | Ω     | DC500V  |
|                  | I/O Capacitance           | C <sub>I/O</sub>   |                  | 0.8  | 1.5   | pF<br>f=1MHz  |

# Reference Data

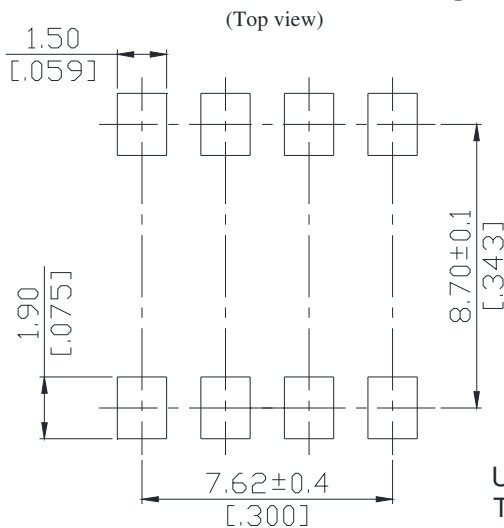


### Taping Specifications for Surface Mount Devices



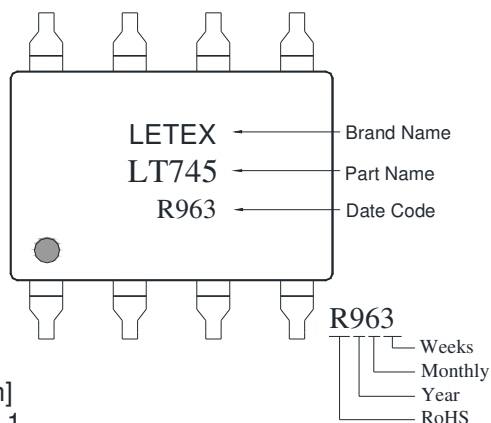
| TYPE | B0±0.1 | F0±0.1 | W0±0.1 | 15"REEL/PCS |
|------|--------|--------|--------|-------------|
| 8P   | 10.3   | 11.5   | 24     | 1000        |

### Recommended Mounting Pad



### Marking

(Each photo MOS Relay shall be marked with the following information)



- Note: 1. There shall be leader of 230 mm minimum which may consist of carrier and or cover tape follower by a minimum of 160 mm of carrier tape sealed with cover tape.  
 2. There shall be a minimum of 160 mm of empty component pockets sealed with cover tape.  
 3. Devices are pockets in accordance with EIA standard EIA-481-A and specifications given above.